[Causes/processes involved/keys to judgment]

A dent formed at panel abrasion for dry film lamination or in a previous process to the lamination remains after forming conductor pattern. Etching of conductor due to poor dry film adhesion is observed in some cases. (Multilayer lamination and material handling prior to dry film lamination)

1-2-2-5 ダメージ欠け/损伤的缺口 / Nick by board damage

【特徴】回路形成後に削り取られたり、衝撃により 欠けた様相の欠け

【特征】图形转移后被切削或者受冲击的缺口。

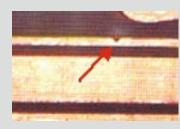
[Characteristics] The nick looks like being engraved or chipped by an impact after forming conductor pattern.

【原因・判断ポイント・発生工程】回路形成後に鋭利なものが当たって回路のコーナーが削り取られたり、硬質端子めっき部が衝撃を受けて欠け落ちたりして出来たもの(回路形成後のマテハン)

【原因、判断要点、发生工序】图形转移后,线路的 拐角碰撞锋利的物体被切削,或者硬质插脚镀层受到 冲击而欠缺所引起的(图形转移后的搬运)。

[Causes/processes involved/keys to judgment]

A sharp object hits and engraves the corner of a conductor after it is formed, or the hard gold plating of a edge board contact is chipped by an impact. (Material handling after forming conductor pattern)



【コメント】 顕微鏡倍率×

^{【注释】} 显微镜倍率×

[Coments]
Magnification: ×



積ニッケル金めっき端 子部の割れ状欠け 顕微鏡倍率×

[注释] 镀镍金插脚的断裂状态 的缺口 显微镜倍率 ×

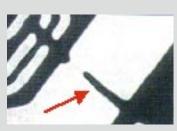
[Coments]
Chipped nickel/gold
plated contact
Magnification: ×

1-2-2-6 AWF 汚れ欠け/ AWF 玷污的缺口 / Chipping by stained AWF Nick by stained phototool

【特徴】導体部のシャープな欠け。同一ケ所、同一 形状欠けが多発することが特徴

【特征】在导线上有轮廓清晰的缺口, 其特点是经常 发生在同一个位置、同一种形状。

[Characteristics] Well defined nick of a conductor. Occurs in many boards at the same place and in the same shape



【コメント】 顕微鏡倍率×

[注释] 显微镜倍率 ×

[Coments]
Magnification: ×